



Material Content Data Sheet



Sales Product Name		ILD8150		Issued		2. August 2019		
MA#		MA003558932						
Package		PG-DSO-8-73		Weight*		80.43 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.113	1.38	1.38	13841	13841
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		105	
	non noble metal	zinc	7440-66-6	0.034	0.04		418	
	non noble metal	iron	7439-89-6	0.673	0.84		8369	
wires	non noble metal	copper	7440-50-8	27.330	33.98	34.87	339813	348705
	noble metal	palladium	7440-05-3	0.001	0.00		17	
	non noble metal	copper	7440-50-8	0.138	0.17	0.17	1715	1732
encapsulation	organic material	carbon black	1333-86-4	0.149	0.19		1856	
	plastics	epoxy resin	-	4.827	6.00		60014	
	inorganic material	silicondioxide	60676-86-0	44.785	55.69	61.88	556834	618704
leadfinish	non noble metal	tin	7440-31-5	0.814	1.01	1.01	10119	10119
plating	noble metal	silver	7440-22-4	0.090	0.11	0.11	1114	1114
glue	plastics	acrylic resin	-	0.102	0.13		1273	
	noble metal	silver	7440-22-4	0.363	0.45	0.58	4512	5785
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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